

Title (en)

A BTE/CIC AUDITORY DEVICE AND MODULAR CONNECTOR SYSTEM THEREFOR

Title (de)

HINTER-DEM-OHR/VOLLSTÄNDIG-IN-DEM-OHR HÖRGERÄT UND MODULARES VERBINDUNGSSYSTEM H

Title (fr)

DISPOSITIF AUDITIF BTE/CIC ET SYSTEME DE CONNECTEUR MODULAIRE ASSOCIE

Publication

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Application

**EP 03795635 A 20030829**

Priority

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Abstract (en)

[origin: WO2004025990A1] An earpiece auditory device includes a behind-the-ear (BTE) component, which includes processing circuitry. In an embodiment, the device also includes a completely-in-canal (CIC) component, shaped to fit into the ear canal of the user such that it touches the bony portion of the ear canal. In some embodiments, the CIC component includes either a universal fit or a custom fit ear mold. The custom fit ear mold can be fabricated using a rapid prototyping technology, in which the contours of the users'ear canal are scanned, and the scan data is used either directly or indirectly to replicate the ear canal contours of that user into the custom fit ear mold. In some embodiments, the ear mold is detachably interconnected with a speaker module, preferably using either an intermediate sleeve or a detachable locking pin assembly. In another embodiment, the speaker module is permanently encapsulated within the ear mold.

IPC 8 full level

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DOCDB simple family (publication)

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